

ABSTRACT

A wiring board obtained by coating a copper paste on a ceramic green sheet and firing it to form a conductor layer and an insulating layer, the copper paste comprising a copper powder, an organic vehicle and at least one selected from the group consisting of: an SiO_2 particle having an average particle size of 50 nm or less; and a ceramic particle having an average particle size of 100 nm or less and non-vitrifiable after sintering.